Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **OUTPUT FILTER**
2. **LOOP FILTER**
3. **INPUT**
4. **V +**
5. **TIMING RES**
6. **TIMING CAP**
7. **GND**
8. **OUTPUT**

**3**

**4**

**2**

**1**

**8**

**7**

**5 6**

**.064”**

**.063”**

**LM567C**

**MASK REF**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: FLOATING**

**Mask Ref: LM567C**

**APPROVED BY: DK DIE SIZE .063” X .064” DATE: 6/22/18**

**MFG: NATIONAL THICKNESS .014” P/N: LM567**

**DG 10.1.2**

#### Rev B, 7/19/02